

FIG. 1

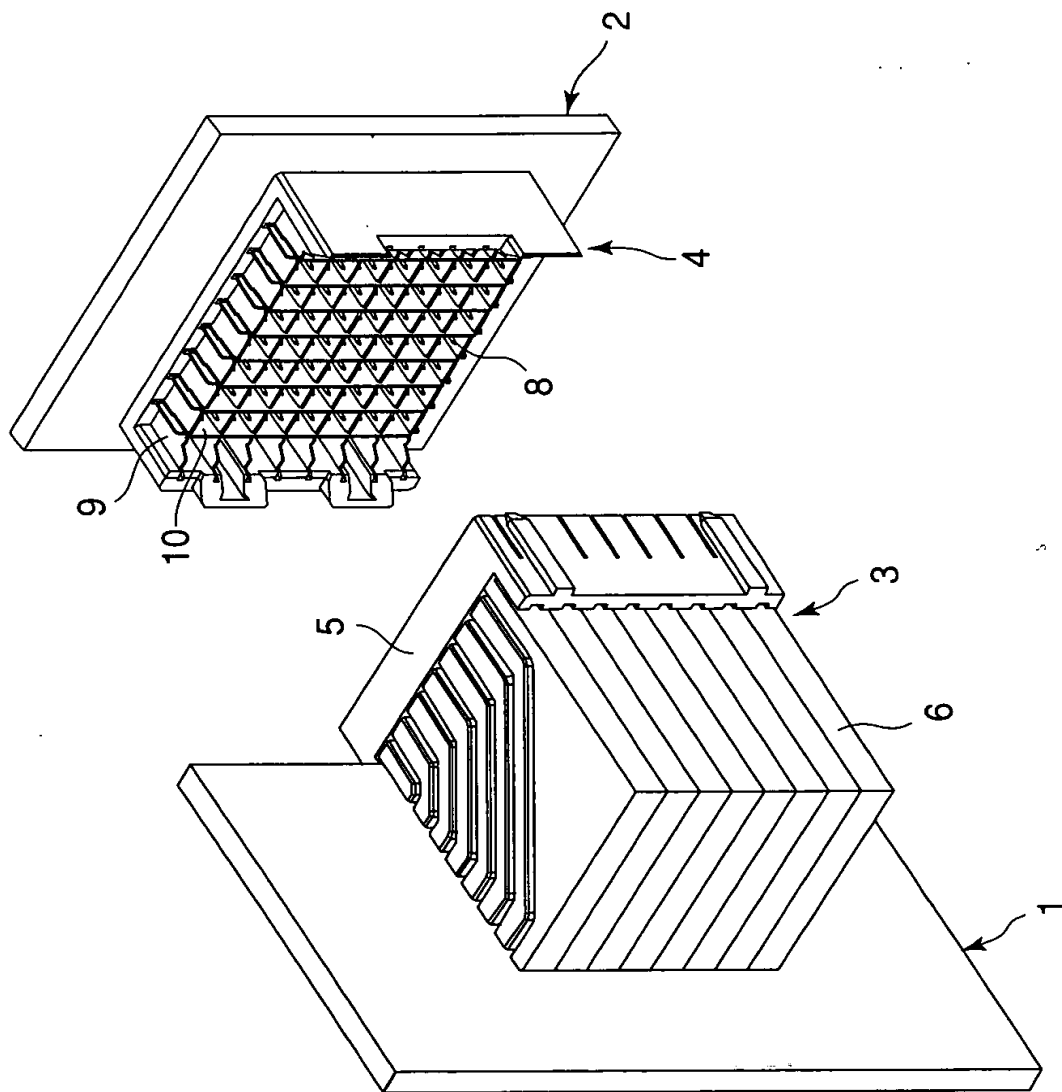


FIG. 2

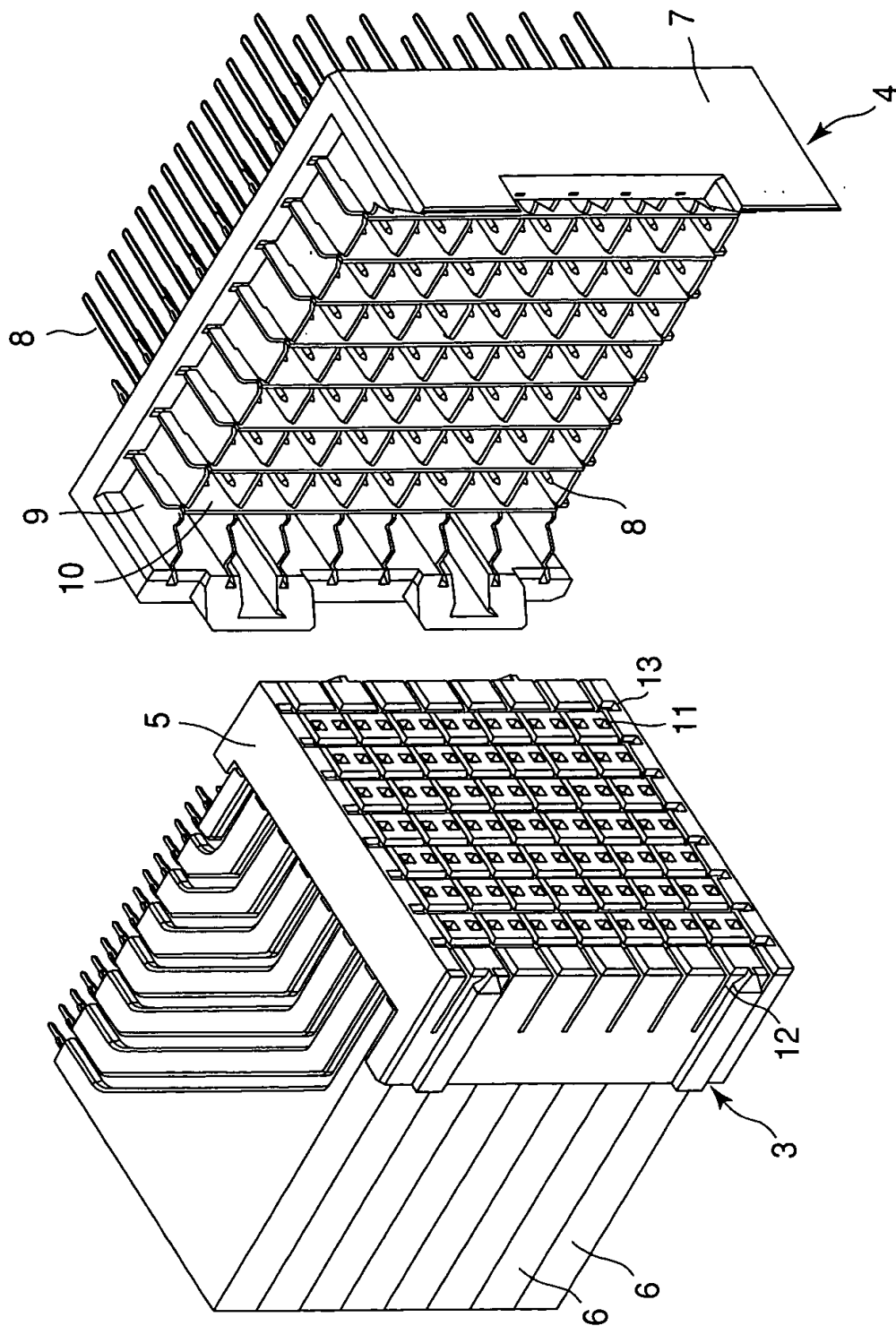


FIG. 3

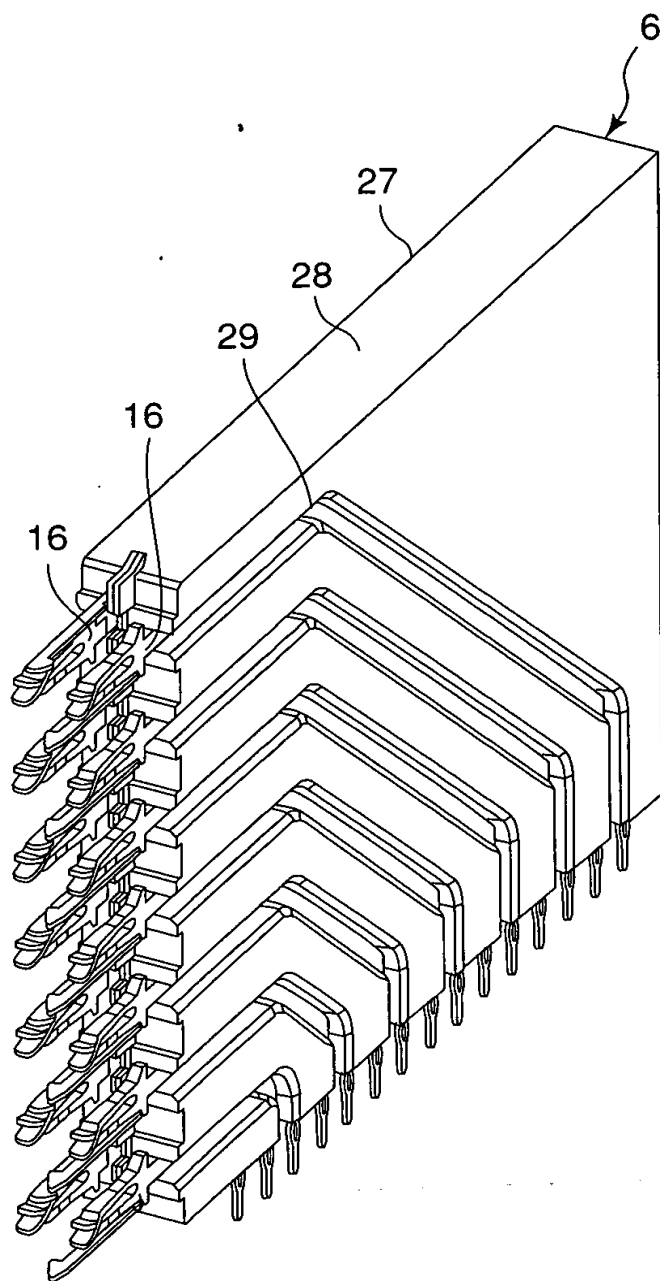


FIG. 4

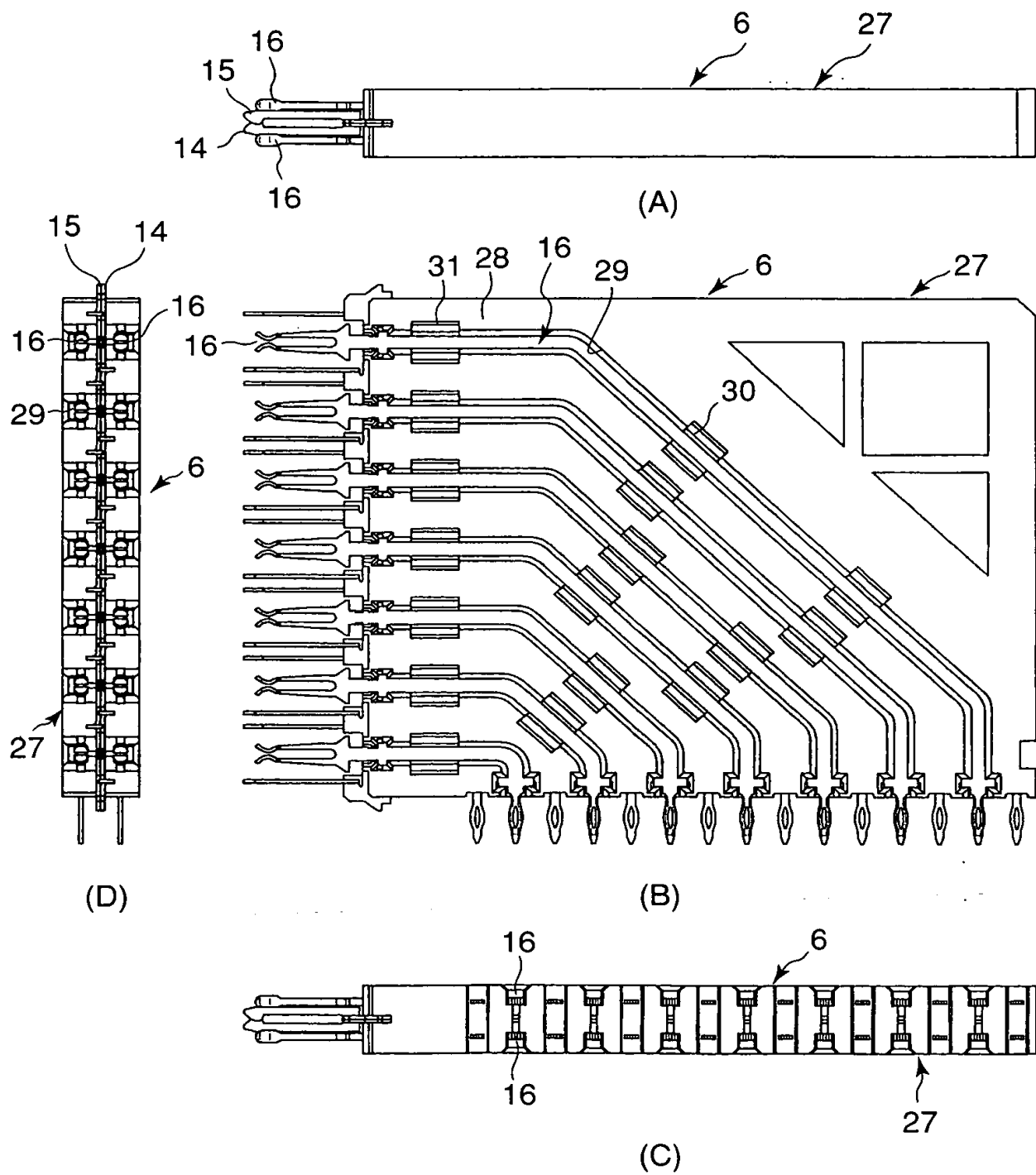


FIG. 5

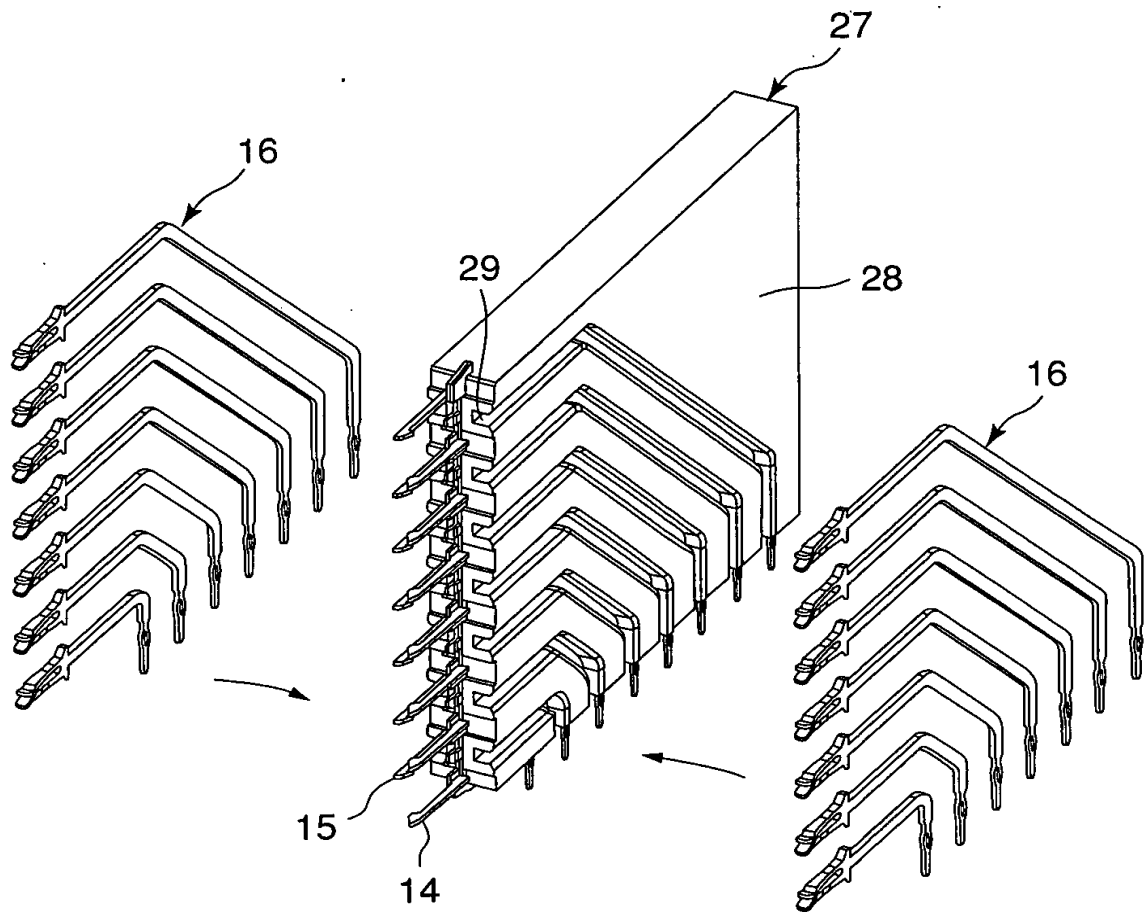


FIG. 6

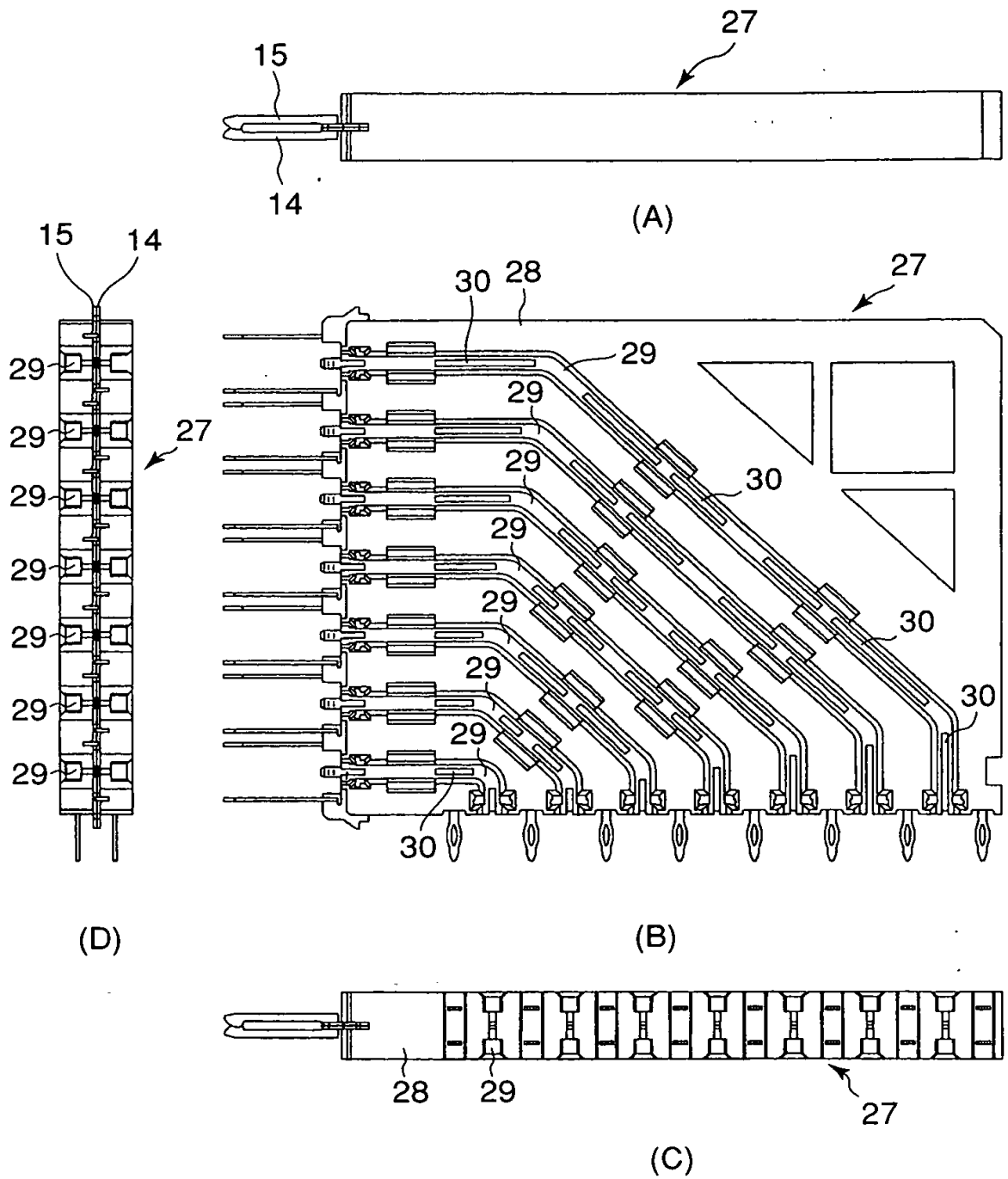


FIG. 7

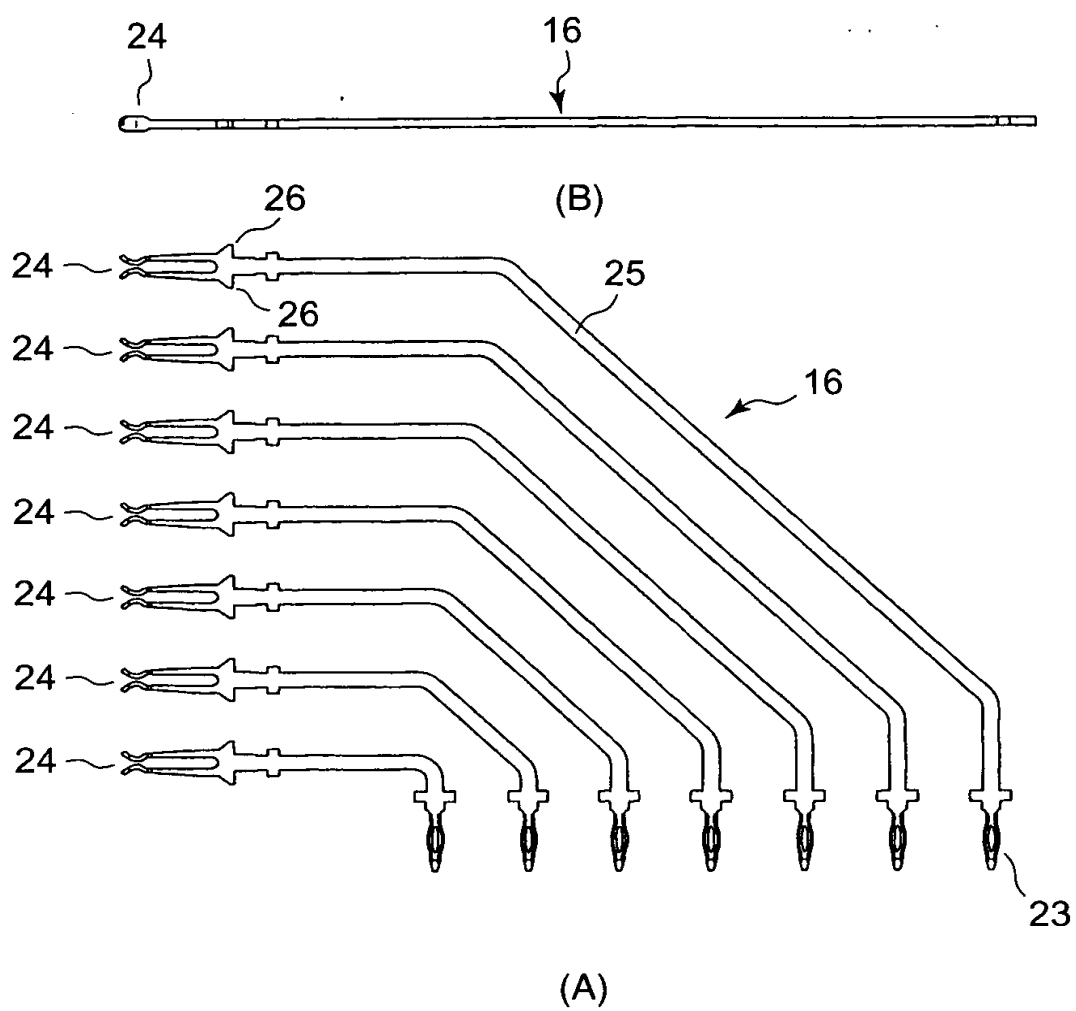
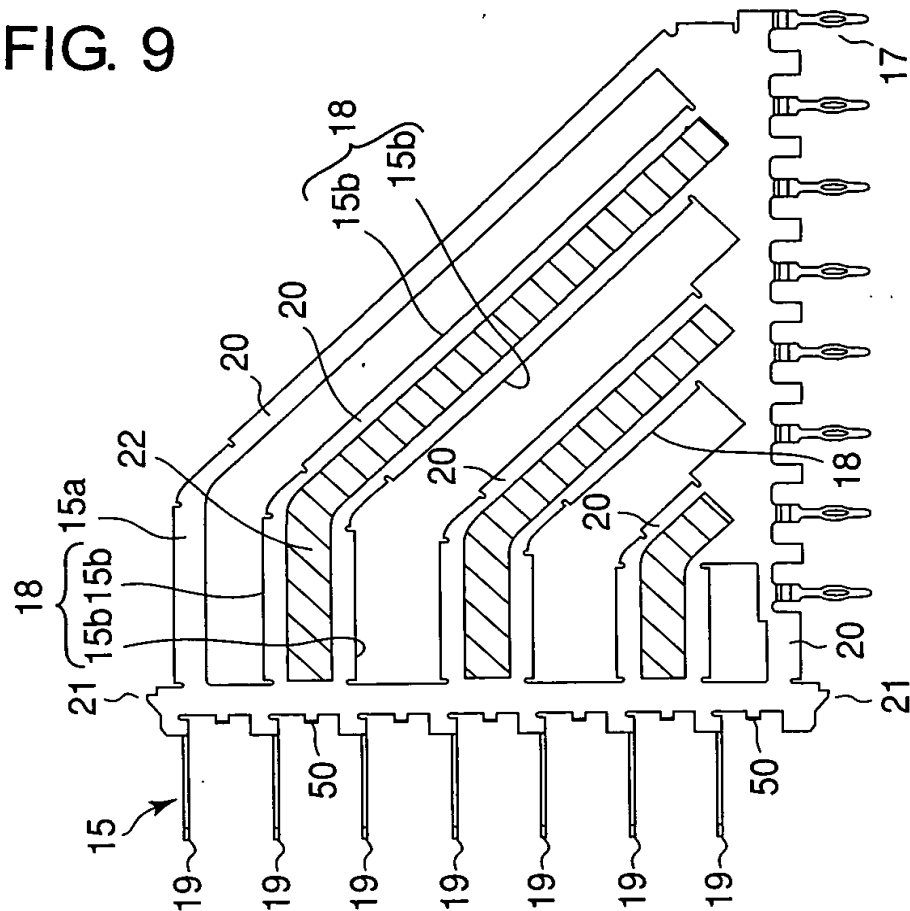


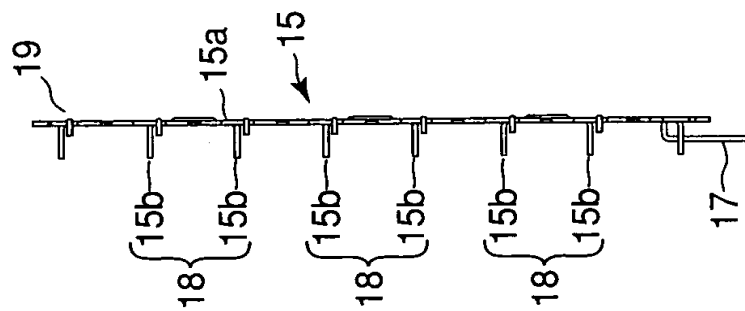




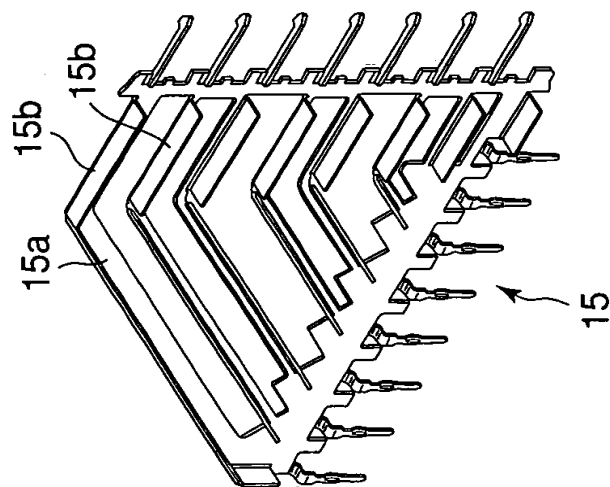
FIG. 9



(A)



(B)



(C)

FIG. 10

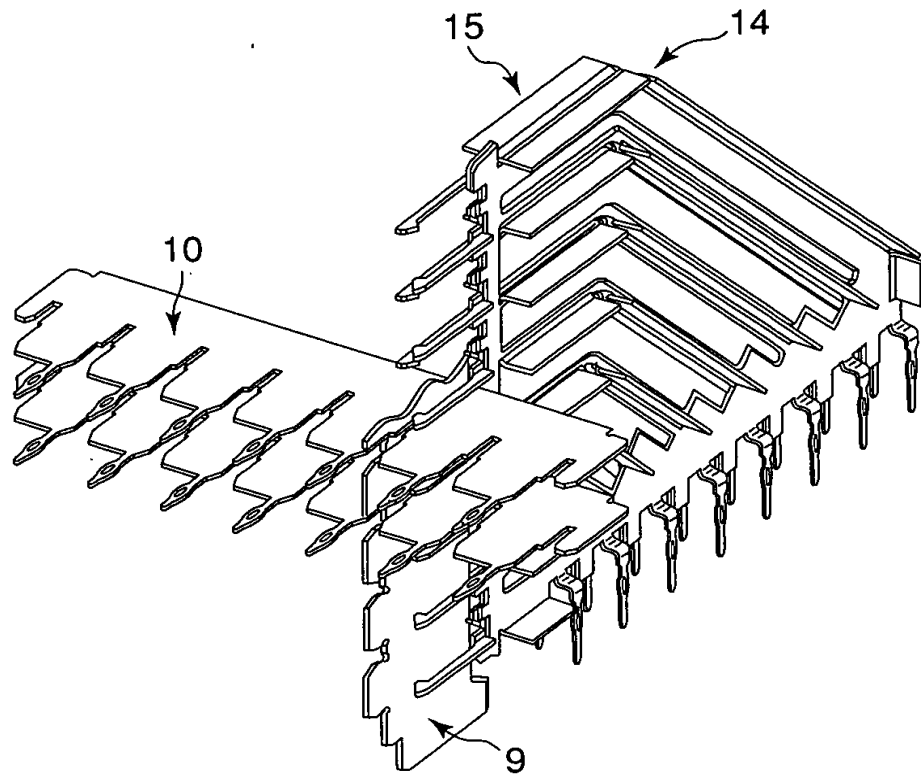


FIG. 11

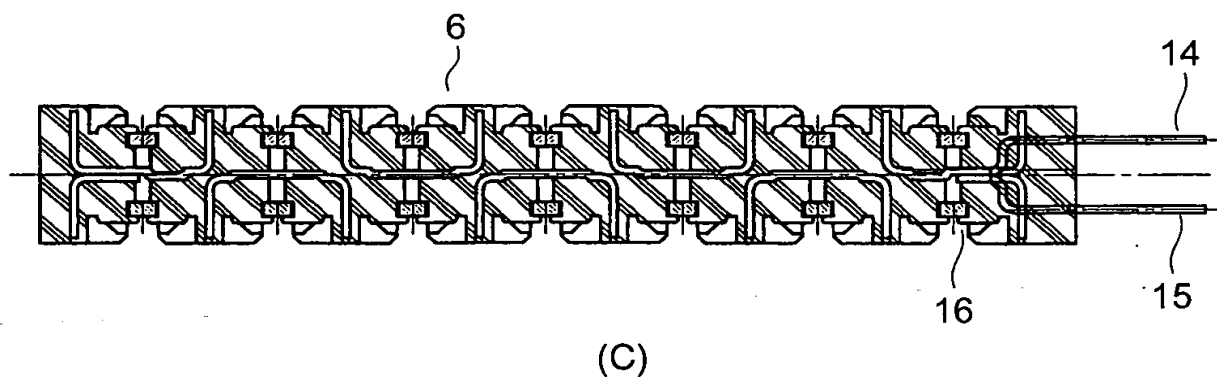
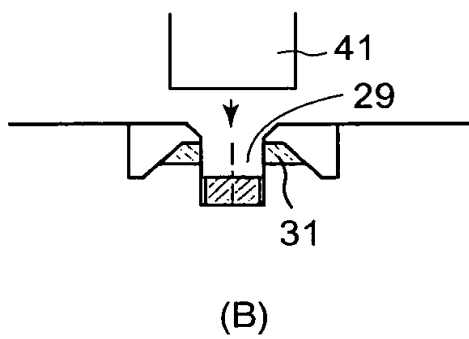
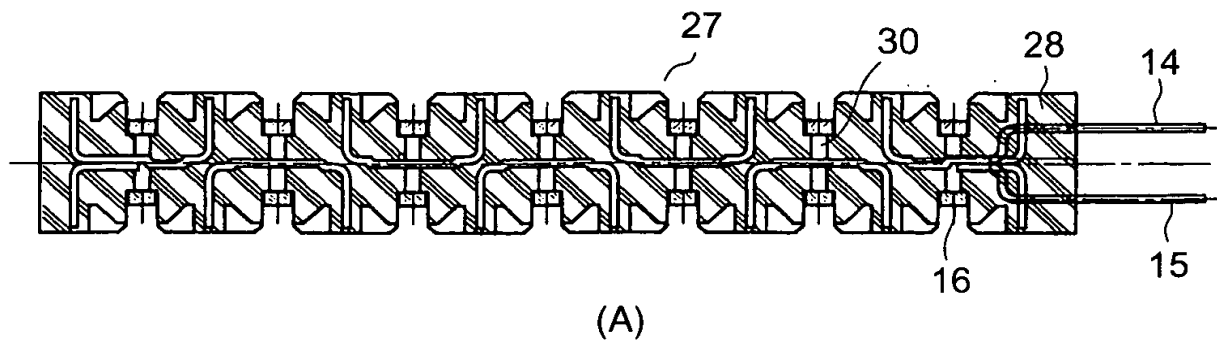
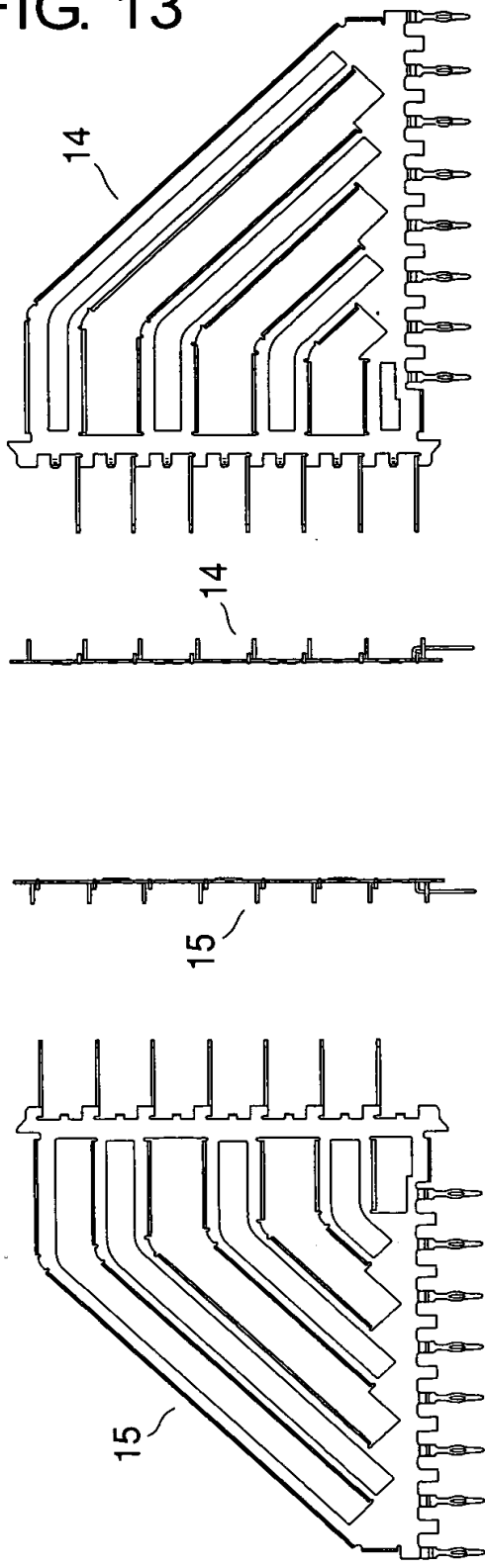
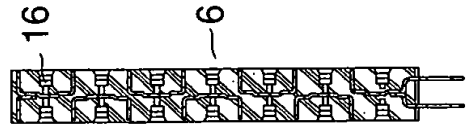


Figure 1 consists of five perspective views (A-E) of a multi-layered electronic component assembly.   
 (A) Top view: Shows a grid of components 11 on a substrate 12. A central block 5 is surrounded by side rails 13.   
 (B) Side view: Shows the profile of the assembly with a base 5 and a top layer 33.   
 (C) Another side view: Shows a different profile with a base 5 and a top layer 12.   
 (D) Front view: Shows a series of vertical elements 5 on a base 12.   
 (E) Another front view: Shows a series of vertical elements 5 on a base 12.   
 Various components are labeled with numbers 11, 12, 13, 33, 34, 35, and 5.

FIG. 13

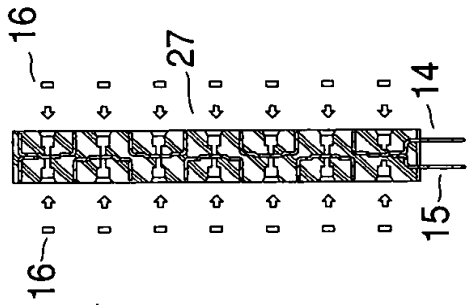


(A)



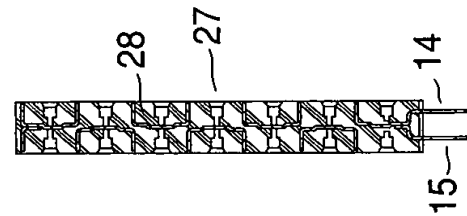
(H)

(B)



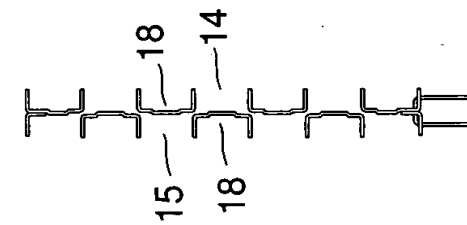
(G)

(C)



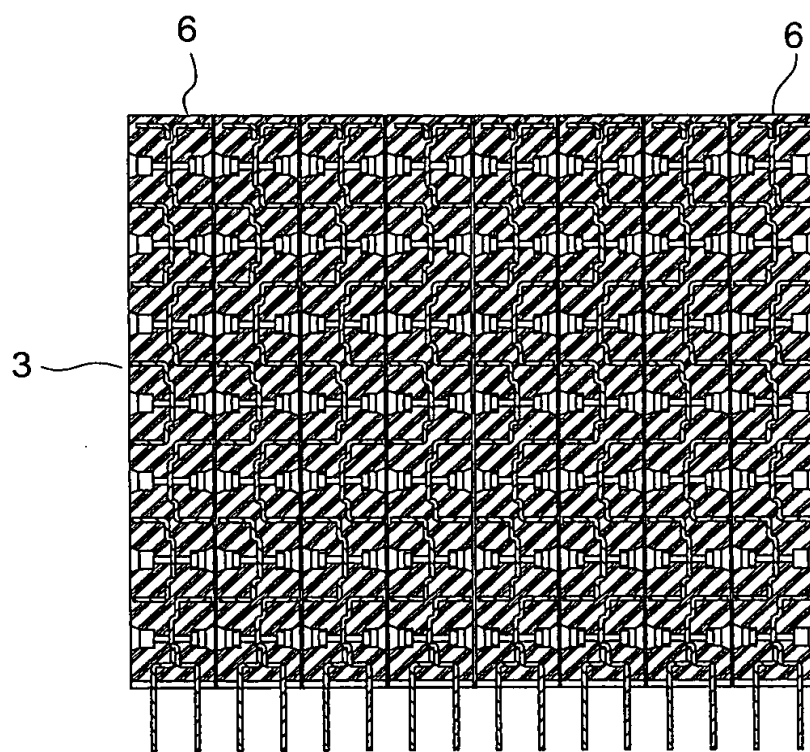
(F)

(D)

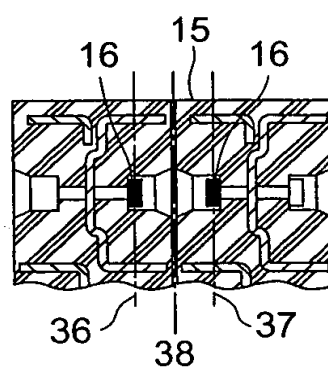


(D)

FIG. 14



(A)



(B)

FIG. 15

